

29. A method for forming an electronic structure, comprising:  
bonding a mineral layer to a metallic plate; and  
bonding an adhesion promoter layer to the mineral layer such that said bonding to the  
mineral layer is moisture resistant.

**Remarks**

Claims 10-29 are currently pending, wherein claims 28 and 29 have been amended herein.

**Response to Restriction Requirement**

In response to the Restriction Requirement dated June 12, 2002, Applicants hereby provisionally elect Group I, claims 10-29, drawn to a method for forming an electronic structure, classified in class 438, subclass 118. This election is made with traverse, and Applicants hereby reserve the right to file a divisional application in connection with unelected claims drawn to an electronic structure. Applicants note that claims 28 and 29, as amended herein, are drawn to a method for forming an electronic structure. Thus, although the Office Action Restriction Requirement mailed 06/12/2002 placed claims 10-27 in Group I, drawn to a method for forming an electronic structure, Applicants consider claims 28 and 29 also be in Group I as a consequence of being amended herein.

With regard to the Restriction Requirement, Applicants respectfully submit that the subject matter of all claims 10-29 is sufficiently related that a thorough search for the subject matter of any one group of claims would encompass a search for the subject matter of the remaining claims. Thus, Applicants respectfully submit that the search and the examination of the entire application could be made without serious burden. See MPEP § 803, in which it is stated

that "if the search and examination of the entire application can be made without serious burden, the Examiner must examine it on the merits" (emphasis added). Applicants respectfully submit that this policy should apply in the present application in order to avoid unnecessary delay and expense to Applicants and duplicative examination by the Patent Office.

Should the Examiner require or request anything further from Applicants prior to examination, the Examiner is requested to contact Applicants' undersigned representative at the telephone number below. Otherwise, Applicants request early and favorable examination on the merits.

Jack P. Friedman  
Jack P. Friedman  
Reg. No. 44,688

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Schmeiser, Olsen & Watts  
3 Lear Jet Lane - Suite 201  
Latham, New York 12110  
(518) 220-1850

**Appendix A. Identification of Amended Material**

28. (AMENDED) [An electronic structure] A method for forming an electronic structure, comprising:

bonding a mineral layer to a metallic plate; and

covalently bonding an adhesion promoter layer to the mineral layer.

29. (AMENDED) [An electronic structure] A method for forming an electronic structure, comprising:

bonding a mineral layer to a metallic plate; and

bonding an adhesion promoter layer to the mineral layer such that said bonding to the mineral layer is moisture resistant.